

Abstract Submitted
for the MAR07 Meeting of
The American Physical Society

First-principles study of direct electron tunneling through ultra-thin SiO₂ layers JOONGOO KANG, K.J. CHANG, Department of Physics, Korea Advanced Institute of Science and Technology, South Korea, Y.-H. KIM, Department of Materials Science and Engineering, University of Seoul, South Korea — As the size of metal-oxide-semiconductor devices is scaled down to the sub-10-nm regime, the thickness of SiO₂ insulating layers reaches the range of 1-2 nm. Then, gate leakage current is unavoidable due to direct tunneling of electrons. In this work, we study the electron tunneling current through thin gate oxide layers for various Si(100)/SiO₂ interface models, which have different oxide thicknesses and crystal phases. We use a combined approach of the local-density-functional approximation and the matrix Green's function method. We test oxide layers in the α -quartz, tridymite, and amorphous structures, which are sandwiched between two Si(100) electrodes. We find that Si induced gap states result from a decay of the silicon valence (conduction) band wave functions into the oxide region. The gate leakage current between two p+ Si electrodes is exponentially reduced as the oxide thickness increases, with the almost same decay rate of -1 decade/0.2 nm, regardless of the structure of oxide layers. We also find that the gate leakage current is affected by introducing interface roughness and oxygen vacancies in the oxide.

Joongoo Kang
Department of Physics, Korea Advanced Institute of Science
and Technology, South Korea

Date submitted: 20 Nov 2006

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